

Amendments to the Specification:

Please replace the paragraph on page 25, lines 9-25 with the following amended paragraph:

FIGS. 7 and 7A illustrates an arrangement 700 for simultaneously exercising a plurality (four shown in FIG. 7) of electronic components 702 which are springed semiconductor devices. Each of the springed semiconductor devices 702 (compare 518) has elongate interconnection elements which are spring contact elements extending from a surface thereof. A corresponding plurality (eight shown in FIG. 7A) of socket substrates 704 (compare 504) have capture pads 706 (six shown, per socket substrate) which are suitably pit-terminals (compare 506) for socketably receiving the free ends of the elongate interconnection elements, in any of the manners described hereinabove. The socket substrates 704 are all suitably mounted to and electrically connected to a common support/interconnection substrate 708 (compare 502) in any of the manners described hereinabove. No particular connections are illustrated, for illustrative clarity. Exemplary connections from the interconnection substrate 708 to the "outside world" are illustrated in this example as a plurality of pogo pins 710. The springed semiconductor devices 702 are held against the corresponding socket substrate 704 in any suitable manner, such as has been described hereinabove (e.g., housings 520 and 550, test head 630, or the like), as is illustrated by the arrows 712. In this manner, a number (such as eight) of individual springed semiconductor devices [[704]] 702 can reversibly be connected to by an external device or system (compare 658). As alternatively shown in Figure 7, the springed semiconductor devices 702 can alternatively be unsingulated dies of a semiconductor wafer 701, which is depicted in dashed lines in Figure 7 indicating that wafer 701 is an alternative configuration.